Data Sheet | March 1999 | FN2802.3

Decimating Digital Filter

The HSP43220/883 Decimating Digital Filter is a linear phase low pass decimation filter which is optimized for filtering narrow band signals in a broad spectrum of a signal processing applications. The HSP43220/883 offers a single chip solution to signal processing application which have historically required several boards of ICs. This reduction in component count results in faster development times, as well as reduction of hardware costs.

The HSP43220/883 is implemented as a two stage filter structure. As seen in the Block Diagram, the first stage is a High Order Decimation Filter (HDF) which utilizes an efficient decimation (sample rate reduction) technique to obtain decimation up to 1024 through a coarse low-pass filtering process. The HDF provides up to 96dB aliasing rejection in the signal pass band. The second stage consists of a Finite Impulse Response (FIR) decimation filter structured as a transversal FIR filter with up to 512 symmetric taps which can implement filters with sharp transition regions. The FIR can perform further decimation by up to 16 if required, while preserving the 96dB aliasing attenuation obtained by the HDF. The combined total decimation capability is 16,384.

The HSP43220/883 accepts 16-bit parallel data in 2's complement format at sampling rates up to 30MSPS. It provides a 16-bit microprocessor compatible interface to simplify the task of programming and three-state outputs to allow the connection of several ICs to a common bus. The HSP43220/883 also provides the capability to bypass either the HDF or the FIR for additional flexibility.

Features

- This Circuit is Processed in Accordance to MIL-STD-883 and is Fully Conformant Under the Provisions of Paragraph 1.2.1.
- Single Chip Narrow Band Filter with up to 96dB Attenuation
- DC to 25.6MHz Clock Rate
- 16-Bit 2's Complement Input
- 20-Bit Coefficients in FIR
- 24-Bit Extended Precision Output
- Programmable Decimation up to a Maximum of 16,384
- Standard 16-Bit Microprocessor Interface
- Filter Design Software Available DECI•MATE™

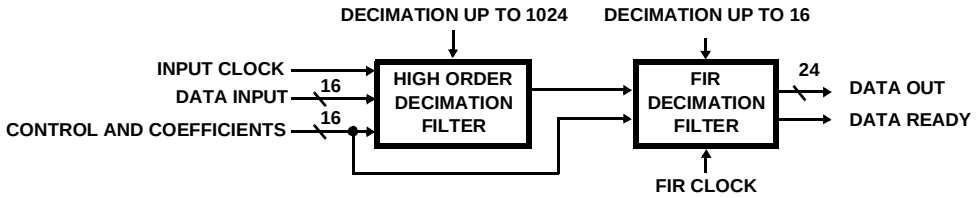
Applications

- Very Narrow Band Filters
- Zoom Spectral Analysis
- Channelized Receivers

Ordering Information

PART NUMBER	TEMP. RANGE (^{O}C)	PACKAGE	PKG. NO.
HSP43220GM-15/883	-55 to 125	84 Ld PGA	G84.A
HSP43220GM-25/883	-55 to 125	84 Ld PGA	G84.A

Block Diagram



CAUTION: These devices are sensitive to electrostatic discharge; follow proper IC Handling Procedures.
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Absolute Maximum Ratings

Supply Voltage 8V
Input, Output Voltage . . . . . GND -5V to V_{CC} 0.5V
ESD Rating . . . . . Class 1

Operating Conditions

Voltage Range . . . . . +4.5V to 5.5V
Temperature Range . . . . . -55^oC to 125^oC

Thermal Information

Thermal Resistance (Typical, Note 1)	θ_{JA} ($^oC/W$)	θ_{JC} ($^oC/W$)
PGA Package	35	5

Maximum Package Power Dissipation at 125^oC
PGA Package 1.52
Maximum Junction Temperature . . . . . 175^oC
Maximum Storage Temperature Range . . . . . -65^oC to 150^oC
Maximum Lead Temperature (Soldering 10s) . . . . . 300^oC

Die Characteristics

Number of Gates 48,250

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

TABLE 1. DC ELECTRICAL PERFORMANCE SPECIFICATIONS

Devices Guaranteed and 100% Tested

PARAMETER	SYMBOL	TEST CONDITIONS	GROUP A SUB-GROUPS	TEMP (^oC)	LIMITS		UNITS
					MIN	TYP	
Logical One Input Voltage	V_{IH}	V_{CC} = 5.5V	1, 2, 3	$-55 \le T_A \le 125$	2.2	-	V
Logical Zero Input Voltage	V_{IL}	V_{CC} - 4.5V	1, 2, 3	$-55 \le T_A \le 125$	-	0.8	V
Output HIGH Voltage	V_{OH}	I_{OH} = 400µA, V_{CC} = 4.5V (Note 2)	1, 2, 3	$-55 \le T_A \le 125$	2.6	-	V
Output LOW Voltage	V_{OL}	I_{OL} = 2.0mA V_{CC} = 4.5V (Note 2)	1, 2, 3	$-55 \le T_A \le 125$	-	0.4	V
Input Leakage Current	I_I	V_{IN} = V_{CC} or GND, V_{CC} = 5.5V	1, 2, 3	$-55 \le T_A \le 125$	-10	+10	µA
Output Leakage Current	I_O	V_{OUT} = V_{CC} or GND, V_{CC} = 5.5V	1, 2, 3	$-55 \le T_A \le 125$	-10	+10	µA
Clock Input High	V_{IHC}	V_{CC} = 5.5V	1, 2, 3	$-55 \le T_A \le 125$	3.0	-	V
Clock Input Low	V_{ILC}	V_{CC} = 4.5V	1, 2, 3	$-55 \le T_A \le 125$	-	0.8	V
Standby Power Supply Current	I_{CCSB}	V_{IN} = V_{CC} or GND, V_{CC} = 5.5V, Outputs Open	1, 2, 3	$-55 \le T_A \le 125$	-	500	µA
Operating Power Supply Current	I_{CCOP}	f = 15.0MHz, V_{CC} = 5.5V (Note 3)	1, 2, 3	$-55 \le T_A \le 125$	-	120	mA
Functional Test	FT	(Note 4)	7, 8	$-55 \le T_A \le 125$	-	-	

NOTES:

2. Interchanging of force and sense conditions is permitted.
3. Operating supply current is proportional to frequency, typical rating is 8mA/MHz.
4. Tested as follows: f = 1MHz, V_{IH} = 2.6, V_{IL} = 0.4, $V_{OH} \ge 1.5V$, $V_{OL} \le 1.5V$, V_{IHC} = 3.4V and V_{ILC} = 0.4V.

TABLE 2. AC ELECTRICAL PERFORMANCE SPECIFICATIONS

Devices Guaranteed and 100% Tested

PARAMETER	SYMBOL	(NOTES) (NOTE 5)	GROUP A SUB-GROUPS	TEMP (^oC)	-15 (15MHz)		-25 (25.6MHz)		UNITS
					MIN	MAX	MIN	MAX	
Input Clock Period	t_{CK}		9, 10, 11	$-55 \le T_A \le 125$	66	-	39	-	ns
FIR Clock Period	t_{FIR}		9, 10, 11	$-55 \le T_A \le 125$	66	-	39	-	ns
Clock Pulse Width Low	t_{SPWL}		9, 10, 11	$-55 \le T_A \le 125$	26	-	16	-	ns
Clock Pulse Width High	t_{SPWH}		9, 10, 11	$-55 \le T_A \le 125$	26	-	16	-	ns
Clock Skew Between FIR_CLK and CK_IN	t_{SK}		9, 10, 11	$-55 \le T_A \le 125$	0	T_{FIR} -25	0	T_{FIR} -19	ns
$\overline{\text{RESET}}$ Pulse Width Low	t_{RSPW}		9, 10, 11	$-55 \le T_A \le 125$	4 T_{CK}	-	4 T_{CK}	-	ns
Recovery Time On $\overline{\text{RESET}}$	t_{RTRS}		9, 10, 11	$-55 \le T_A \le 125$	8 T_{CK}	-	8 T_{CK}	-	ns
$\overline{\text{ASTARTIN}}$ Pulse Width Low	t_{AST}		9, 10, 11	$-55 \le T_A \le 125$	T_{CK} +10	-	T_{CK} +10	-	ns
$\overline{\text{STARTOUT}}$ Delay From CK_IN	t_{STOD}		9, 10, 11	$-55 \le T_A \le 125$	-	35	-	20	ns
$\overline{\text{STARTIN}}$ Setup to CK _IN	t_{STIC}		9, 10, 11	$-55 \le T_A \le 125$	25	-	15	-	ns
Setup Time on DATA_IN	t_{SET}		9, 10, 11	$-55 \le T_A \le 125$	20	-	16	-	ns
Hold Time on All Inputs	t_{HOLD}		9, 10, 11	$-55 \le T_A \le 125$	0	-	0	-	ns
Write Pulse Width Low	t_{WL}		9, 10, 11	$-55 \le T_A \le 125$	26	-	15	-	ns
Write pulse Width High	t_{WH}		9, 10, 11	$-55 \le T_A \le 125$	26	-	20	-	ns
Setup Time on Address Bus Before the Rising Edge of Write	t_{STADD}		9, 10, 11	$-55 \le T_A \le 125$	28	-	24	-	ns
Setup Time on Chip Select Before the Rising Edge of Write	t_{STCS}		9, 10, 11	$-55 \le T_A \le 125$	28	-	24	-	ns
Setup Time on Control Bus Before the Rising Edge of Write	t_{STCB}		9, 10, 11	$-55 \le T_A \le 125$	28	-	24	-	ns
DATA_RDY Pulse Width Low	t_{DRPWL}		9, 10, 11	$-55 \le T_A \le 125$	$2T_{FIR}$ -20	-	$2T_{FIR}$ -10	-	ns
DATA_OUT Delay Relative to FIR_CK	t_{FIRDV}		9, 10, 11	$-55 \le T_A \le 125$	-	50	-	35	ns
DATA_RDY Valid Delay Relative to FIR_CK	t_{FIRDR}		9, 10, 11	$-55 \le T_A \le 125$	-	35	-	25	ns
DATA_OUT Delay Relative to OUT_SELH	t_{OUT}		9, 10, 11	$-55 \le T_A \le 125$	-	30	-	25	ns
Output Enable to Data Out Valid	t_{OEV}	Note 6	9, 10, 11	$-55 \le T_A \le 125$	-	20	-	20	ns

NOTES:

5. AC Testing: V_{CC} = 4.5V and 5.5V. Inputs are driven at 3.0V for a Logic “1” and 0.0V for a Logic “0”. Input and output timing measurements are made at 1.5V for both a Logic “1” and “0”. CLK is driven at 4.0V and 0V and measured at 2.0V.
6. Transition is measured at ±200mV from steady state voltage with loading as specified by test load circuit and C_L = 40pF.

TABLE 3. ELECTRICAL PERFORMANCE SPECIFICATIONS

Devices Guaranteed and 100% Tested

PARAMETER	SYMBOL	TEST CONDITIONS	NOTES	TEMP (^{O}C)	-15 (15MHz)		-25 (25.6MHz)		UNITS
					MIN	MAX	MIN	MAX	
CK_IN Pulse Width Low	t_{CH1L}		7, 9	$-55 \le T_A \le 125$	29	-	19	-	ns
CK_IN Pulse Width High	t_{CH1H}		7, 9	$-55 \le T_A \le 125$	29	-	19	-	ns
CK_IN Setup to FIR_CK	t_{CIS}		7, 9	$-55 \le T_A \le 125$	27	-	17	-	ns
CK_IN Hold from FIR_CK	t_{CIH}		7, 9	$-55 \le T_A \le 125$	2	-	2	-	ns
Input Capacitance	C_{IN}	V_{CC} = Open, f = 1MHz, All measurements are referenced to device GND	7	$T_A = 25^{O}C$	-	12	-	12	pF
Output Capacitance	C_{OUT}	V_{CC} = Open, f = 1MHz, All measurements are referenced to device GND	7	$T_A = 25^{O}C$	-	10	-	10	pF
Output Disable Delay	t_{OEZ}		7, 8	$-55 \le T_A \le 125$	-	20	-	20	ns
Output Rise Time	t_{OR}		7, 8	$-55 \le T_A \le 125$	-	8	-	8	ns
Output Fall Time	t_{OF}		7, 8	$-55 \le T_A \le 125$	-	8	-	8	ns

NOTES:

7. Parameters listed in Table 3 are controlled via design or process parameters and are not directly tested. These parameters are characterized upon initial design and after major process and/or design changes.
8. Loading is as specified in the test load circuit with C_L = 40pF.
9. Applies only when H_BYP = 1 or H_DRATE = 0.

TABLE 4. APPLICABLE SUBGROUPS

CONFORMANCE GROUPS	METHOD	SUBGROUPS
Initial Test	100%/5004	-
Interim Test	100%/5004	-
PDA	100%	1
Final Test	100%	2, 3, 8A, 8B, 10, 11
Group A	-	1, 2, 3, 7, 8A, 8B, 9, 10, 11
Groups C and D	Samples/5005	1, 7, 9

Burn-In Circuit

HSP43220/883
TOP VIEW
PINS DOWN

	1	2	3	4	5	6	7	8	9	10	11
A	GND	DATA_ IN 1	DATA_ IN 2	DATA_ IN 4	DATA_ IN 7	DATA_ IN 8	DATA_ IN 11	DATA_ IN 14	VCC	GND	GND
B	$\overline{\text{START IN}}$	$\overline{\text{START OUT}}$	DATA_ IN 0	DATA_ IN 3	DATA_ IN 6	DATA_ IN 13	DATA_ IN 12	DATA_ IN 15	CLK_IN	V_{CC}	DATA_ OUT 1
C	$\overline{\text{ASTART IN}}$	V_{CC}			DATA_ IN 0	DATA_ IN 9	DATA_ IN 10			DATA_ OUT 0	DATA_ OUT 2
D	A1	RESET								DATA_ OUT 3	DATA_ OUT 4
E	$\overline{\text{CS}}$	$\overline{\text{WR}}$	A0						DATA_ OUT 5	DATA_ OUT 3	DATA_ OUT 7
F	C_BUS 10	C_BUS 15	C_BUS 14						DATA_ OUT 9	V_{CC}	DATA_ OUT 8
G	C_BUS 12	C_BUS 11	C_BUS 13						DATA_ OUT 10	GND	DATA_ OUT 11
H	C_BUS 9	V_{CC}								DATA_ OUT 13	DATA_ OUT 12
J	GND	C_BUS 7			OUT_ SELH	GND	FIR_ CK			DATA_ OUT 16	DATA_ OUT 14
K	C_BUS 8	C_BUS 5	C_BUS 4	C_BUS 1	OUT_ $\overline{\text{EMP}}$	V_{CC}	GND	DATA_ OUT 22	DATA_ OUT 19	DATA_ OUT 17	DATA_ OUT 15
L	C_BUS 6	C_BUS 3	C_BUS 2	C_BUS 0	OUT_ $\overline{\text{ENX}}$	DATA_ RDY	V_{CC}	DATA_ OUT 23	DATA_ OUT 21	DATA_ OUT 20	DATA_ OUT 18

BURN-IN CIRCUIT SIGNALS

PIN LEAD	PIN NAME	BURN-IN SIGNAL	PIN LEAD	PIN NAME	BURN-IN SIGNAL	PIN LEAD	PIN NAME	BURN-IN SIGNAL
A1	GND	GND	C1	$\overline{\text{ASTARTIN}}$	F15	F11	DATA_OUT 3	$V_{CC}/2$
A2	DATA_IN 1	F2	C2	V_{CC}	V_{CC}	G1	C_BUS 12	F5
A3	DATA_IN 2	F3	C5	DATA_IN 5	F6	G2	C_BUS 11	F4
A4	DATA_IN 4	F5	C6	DATA_IN 9	F2	G3	C_BUS 13	F6
A5	DATA_IN 7	F8	C7	DATA_IN 10	F3	G9	DATA_OUT 10	$V_{CC}/2$
A6	DATA_IN 8	F1	C10	DATA_OUT 0	$V_{CC}/2$	G10	GND	GND
A7	DATA_IN 11	F4	C11	DATA_OUT 2	$V_{CC}/2$	G11	DATA_OUT 11	$V_{CC}/2$
A8	DATA_IN 14	F7	D1	A1	F14	HI	C_BUS 9	F2
A9	V_{CC}	V_{CC}	D2	$\overline{\text{RESET}}$	F16	H2	V_{CC}	V_{CC}
A10	GND	GND	D10	DATA_OUT 3	$V_{CC}/2$	H10	DATA_OUT 13	$V_{CC}/2$
A11	GND	GND	D11	DATA_OUT 4	$V_{CC}/2$	H11	DATA_OUT 12	$V_{CC}/2$
B1	$\overline{\text{STARTIN}}$	F15	E1	$\overline{\text{CS}}$	F11	J1	GND	GND
B2	$\overline{\text{STARTOUT}}$	$V_{CC}/2$	E2	$\overline{\text{WR}}$	F11	J2	C_BUS 7	F8
B3	DATA_IN 0	F1	E3	A0	F13	J5	OUT_SEL	F10
B4	DATA_IN 3	F4	E9	DATA_OUT 5	$V_{CC}/2$	J6	GND	GND
B5	DATA_IN 6	F7	E10	DATA_OUT 6	$V_{CC}/2$	J8	FIR_CK	F0

BURN-IN CIRCUIT SIGNALS (CONTINUED)

PIN LEAD	PIN NAME	BURN-IN SIGNAL	PIN LEAD	PIN NAME	BURN-IN SIGNAL	PIN LEAD	PIN NAME	BURN-IN SIGNAL
B6	DATA_IN 13	F6	E11	DATA_OUT 7	$V_{CC}/2$	J10	DATA_OUT 16	$V_{CC}/2$
B7	DATA_IN 12	F5	F1	C_BUS 10	F3	J11	DATA_OUT 14	$V_{CC}/2$
B8	DATA_IN 15	F8	F2	C_BUS 15	F8	K1	C_BUS 8	F1
B9	CK_IN	F0	F3	C_BUS 14	F7	K2	C_BUS 5	F6
B10	V_{CC}	V_{CC}	F9	DATA_OUT9	$V_{CC}/2$	K3	C_BUS 4	F5
B11	DAT_OUT 1	$V_{CC}/2$	F10	V_{CC}	V_{CC}	K4	C_BUS 1	F2
K5	OUT_$\overline{ENP}$	F9	K11	DATA_OUT 15	$V_{CC}/2$	L6	DATA_$\overline{RDY}$	$V_{CC}/2$
K6	V_{CC}	V_{CC}	L1	C_BUS 6	F7	L7	V_{CC}	V_{CC}
K7	GND	GND	L2	C_BUS 3	F4	L8	DATA_OUT 23	$V_{CC}/2$
K8	DATA_OUT 22	$V_{CC}/2$	L3	C_BUS 2	F3	L9	DATA_OUT 21	$V_{CC}/2$
K9	DATA_OUT 19	$V_{CC}/2$	L4	C_BUS 0	F1	L10	DATA_OUT 20	$V_{CC}/2$
K10	DATA_OUT 17	$V_{CC}/2$	L5	OUT_$\overline{ENX}$	F9	L11	DATA_OUT 18	$V_{CC}/2$

NOTES:

10. $V_{CC}/2$ (2.7 ±10%) used for outputs only.
11. 47kΩ (±20%) resistor connected to all pins except V_{CC} and GND.
12. V_{CC} = 5.5 ±0.5V.
13. 0.1µF (minimum) capacitor between V_{CC} and GND per position.
14. F0 = 100kHz ±10%, F1 = F0/2, F2 = F1/2....F16 = F15/2, 40% - 60% duty cycle.
15. Input voltage limits: V_{IL} = 0.8 maximum, V_{IH} = 4.5V ±10%.

Metal Topology

DIE DIMENSIONS:

348 x 349.2 x 19 ±1 mils

METALLIZATION:

Type: Si - Al, or Si - Al - Cu
Thickness: 8kÅ

WORST CASE CURRENT DENSITY:

$1.18 \times 10^5 A/cm^2$

GLASSIVATION:

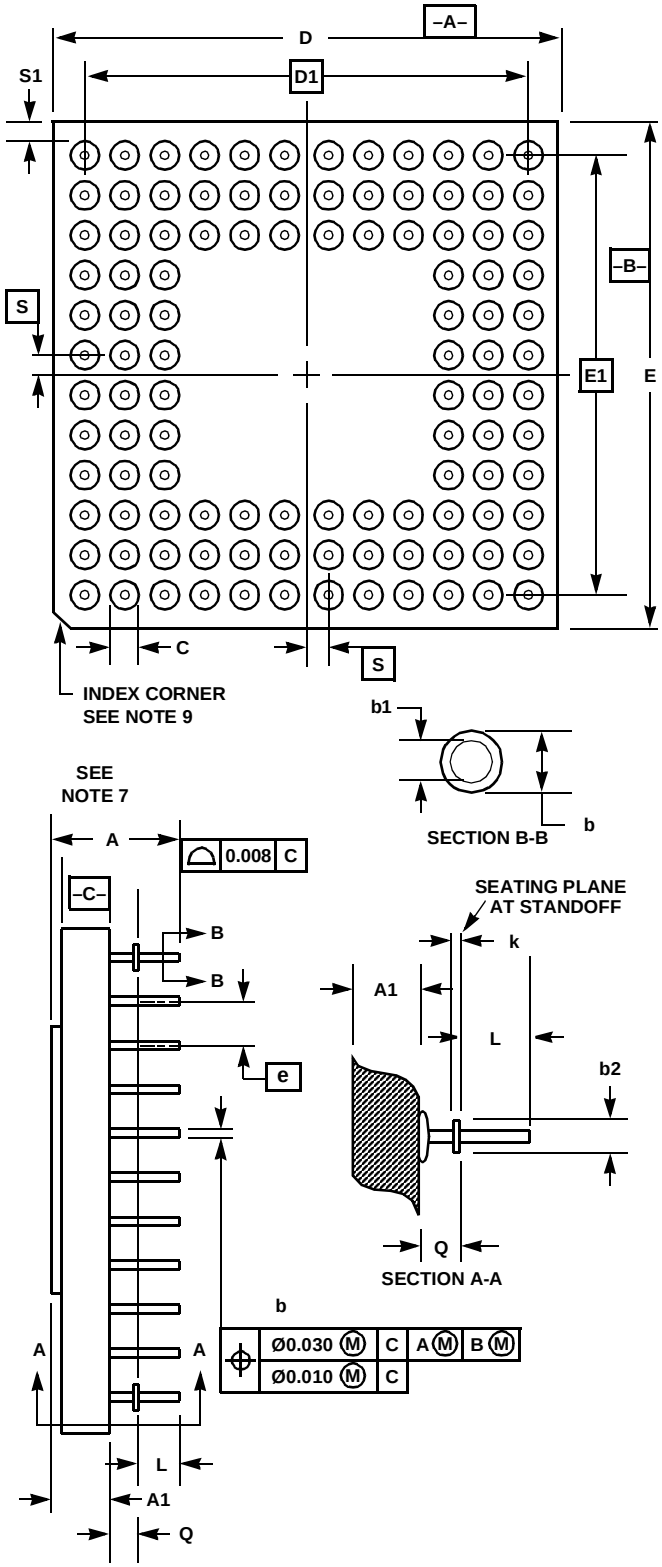
Type: Nitrox
Thickness: 10kÅ

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Ceramic Pin Grid Array Packages (CPGA)



G84.A **MIL-STD-1835 CMGA3-P84C (P-AC)**
84 LEAD CERAMIC PIN GRID ARRAY PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.215	0.345	5.46	8.76	-
A1	0.070	0.145	1.78	3.68	3
b	0.016	0.0215	0.41	0.55	8
b1	0.016	0.020	0.41	0.51	-
b2	0.042	0.058	1.07	1.47	4
C	-	0.080	-	2.03	-
D	1.140	1.180	28.96	29.97	-
D1	1.000 BSC		25.4 BSC		-
E	1.140	1.180	28.96	29.97	-
E1	1.000 BSC		25.4 BSC		-
e	0.100 BSC		2.54 BSC		6
k	0.008 REF		0.20 REF		-
L	0.120	0.140	3.05	3.56	-
Q	0.040	0.060	1.02	1.52	5
S	0.000 BSC		0.00 BSC		10
S1	0.003	-	0.08	-	-
M	11		11		1
N	-	121	-	121	2

Rev. 1 6/28/95

NOTES:

1. “M” represents the maximum pin matrix size.
2. “N” represents the maximum allowable number of pins. Number of pins and location of pins within the matrix is shown on the pinout listing in this data sheet.
3. Dimension “A1” includes the package body and Lid for both cavity-up and cavity-down configurations. This package is cavity up. Dimension “A1” does not include heatsinks or other attached features.
4. Standoffs are intrinsic and shall be located on the pin matrix diagonals. The seating plane is defined by the standoffs at dimensions Q.
5. Dimension “Q” applies to cavity-up configurations only.
6. All pins shall be on the 0.100 inch grid.
7. Datum C is the plane of pin to package interface for both cavity up and down configurations.
8. Pin diameter includes solder dip or custom finishes. Pin tips shall have a radius or chamfer.
9. Corner shape (chamfer, notch, radius, etc.) may vary from that shown on the drawing. The index corner shall be clearly unique.
10. Dimension “S” is measured with respect to datums A and B.
11. Dimensioning and tolerancing per ANSI Y14.5M-1982.
12. Controlling dimension: INCH.